

**Specifications** 

Insulation Resistance



SMD Comm COG Flex, Ceramic, 47 pF, 5%, 50 VDC, COG, SMD, MLCC, FTCAP, Ultra-Stable, 0805, 0.6 mm



| General Information      |                                     |
|--------------------------|-------------------------------------|
| Series                   | SMD Comm COG Flex                   |
| Style                    | SMD Chip                            |
| Description              | SMD, MLCC, FT-CAP, Ultra-<br>Stable |
| Features                 | FT-CAP, Ultra-Stable                |
| RoHS                     | Yes                                 |
| Termination              | Flexible Termination                |
| Marking                  | No                                  |
| AEC-Q200                 | No                                  |
| Typical Component Weight | 11 mg                               |
| Shelf Life               | 78 Weeks                            |
| MSL                      | 1                                   |

| Dimensions |                  |
|------------|------------------|
| Chip Size  | 0805             |
| L          | 2mm +/-0.3mm     |
| W          | 1.25mm +/-0.3mm  |
| Т          | 0.78mm +/-0.20mm |
| S          | 0.6mm MIN        |
| В          | 0.5mm +/-0.25mm  |
|            |                  |

| Capacitance  | 47 pF                     |
|--|---------------------------|
| Measurement Condition  | 1 MHz 1.0Vrms             |
| Tolerance  | 5%                        |
| Voltage DC   | 50 VDC                    |
| Dielectric Withstanding Voltage  | 125 VDC                   |
| Temperature Range  | -55/+125°C                |
| Temp. Coefficient  | COG                       |
| Capacitance Change with<br>Reference to +25°C and 0 VDC<br>Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1 MHz 1.0Vrms        |
| Aging Rate   | 0% Loss/Decade Hour       |

100 GOhms

| Packaging Specifications |           |
|--------------------------|-----------|
| Packaging                | Bulk, Bag |
| Packaging Quantity       | 1         |

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